

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6849208

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shih-Ping Lee	07/26/2021
Tse-Hsien Wu	07/27/2021
Pin-Chieh Huang	07/29/2021
Yu-Hsiang Chien	07/28/2021
Yeh-Yu Chiang	07/27/2021
RECEIVING PARTY DATA	
Name:	Powerchip Semiconductor Manufacturing Corporation
Street Address:	NO.18, LI-HSIN RD. 1, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17394372
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4:	NEW TAIPEI CITY, TAIWAN
ATTORNEY DOCKET NUMBER:	PSMP0011USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	08/04/2021
Total Attachments: 10	
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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

**Title of Invention:
THROUGH SILICON VIA AND METHOD OF MANUFACTURING THE SAME**

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **Powerchip Semiconductor Manufacturing Corporation** having a postal address of _____

NO.18, LI-HSIN RD. 1, HSINCHU SCIENCE PARK, HSINCHU 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Shih-Ping Lee

Date: 2021, 7, 26

Signature: Shih-Ping Lee

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor Tse-Hsien Wu

Date

2021/7/27

Signature

Tse - Hsien Wu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Pin-Chieh Huang

Date:

2021.7.29

Signature: Pin-Chieh Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Hsiang Chien**

Date: 2021.7.28

Signature: Yu Hsiang Chien

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yeh-Yu Chiang

Date: 2021.7.29.

Signature: Yeh-Yu Chiang